

## ATLAS Strip CMOS Fortnightly Meeting - Minutes of 22<sup>nd</sup> July 2014 5pm CET

Attendance: B. Hommels, I. Bloch, I. Gregor D. Muenstermann, M. Stanitzki, R. Nickerson, A. Grillo, Z. Liang, Su Dong, S.Kuehn, T. Huffman

Meeting URL: <https://indico.desy.de/conferenceDisplay.py?confId=10600>

Apologies: C. Buttar, M. Warren

Next Meeting Date: **05/08/14 Tuesday 5pm – 6pm CET**

### Continuing Actions from Previous Meetings

Action on	Action	By
Richard, Steve	Talk to Steve about CERN agreement over shared submissions	15/07/14
Craig, Marcel	Produce document showing tests, irradiations and schedule	ongoing
Renato	Check Purchase Order Arrangements with Tower-Jazz	ongoing
Alex	Check Purchase Order Arrangements with AMS	ongoing

### Actions from this Meeting

Action on	Action	By
Daniel	Communication between Groups	Ongoing
Richard, Marcel	Invite I. Peric to introduce MAPSIBO board	Ongoing
Ivan Peric	Report on Price/Timescale for ordering additional chips from AMS	05/08/2014
Daniel	Check with ALICE concerning Tower submissions	05/08/2014
Alex, Daniel, Vitaliy	Check how to submit AMS H35 via CERN	05/08/2014
Testing Group	Check Specs for submission	05/08/2014

### Agenda

- Minutes/ Actions
- Sensor Status
- Test Preparation Status
- DAQ status
- AOB

### Minutes/Actions

Richard went through the actions from the last meeting. Main points are the arrangements for submission both on Tower-Jazz and on AMS H35. D. Muenstermann is going to check how ALICE did their submission on Tower-Jazz. The preferred method for submitting to AMS is via CERN. There are ongoing discussions on how to make this happen.

The documents by Alex and Vitaly on the test structures and by Craig on the testing are pretty much complete, Action will be closed on the next meeting.

#### Sensor Status

Alex reported on the status of the AMS H35 submission. The files from Ivan have arrived and were very useful. The design work both at UCSC and SLAC is going very well, there are still some timing issues to be fixed. Alex asked the testing group to please read the spec document if there are any open questions. Concerning the costs for submission, the current estimate is about 13000 Euro for the first submission. This is based on a chip size of 14x20 mm. The pad size of 40x40 microns for the Inner pixel was discussed (Details see the spec)

#### Testing Status

Craig reported on the testing status. They have established, that bonding on Alu pads is ok, which is beneficial for irradiation tests. Jens has compiled a useful document on the H35 Chip: [https://twiki.cern.ch/twiki/pub/Atlas/H35StripTestChip/H35\\_Strip\\_Test\\_chip.docx](https://twiki.cern.ch/twiki/pub/Atlas/H35StripTestChip/H35_Strip_Test_chip.docx). Discussion with Craig, Jens, Jaya John, Tony W, and Alan on plans and requirements for chip PCBs, they decided to go for a two PCB system, with initial focus on chip carrier flex makes sense, Keep things as simple as possible (e.g. PSUs are external to PCBs). The work on chip carrier flex has started at Oxford and the Motherboard PCB will follow.

#### DAQ Status

The DAQ firmware modification (for HSIO) have started and the HSIO port to Atlys is happening

#### AOB